

Claims

1. Circuit arrangement (1) on a substrate (2) and comprising
  - at least one semiconductor component (3) arranged on the substrate (2) and having at least one electrical contact surface (31) and
  - at least one connection line (4) arranged on the substrate (2) for electrically contacting the contact surface (31) of the semiconductor component (3), characterized in that
  - the electrical connection line (4) is a part (51) of at least one discrete passive electrical component (5) arranged on the substrate (2).
2. Circuit arrangement in accordance with claim 1, with
  - the discrete passive electrical component (5) being a capacitor (53) and
  - the part (51) being an electrode (531) of the capacitor (53).
3. Circuit arrangement in accordance with claim 1, with
  - the discrete passive electrical component (5) being a coil (54) and
  - the part (51) being a winding (541) of the coil (54).
4. Circuit arrangement in accordance with claim 1, with
  - the discrete passive electrical component (5) being an electrical resistor (52) and
  - the part being a wire resistor (521).
5. Circuit arrangement in accordance with one of claims 1 to 4, with the discrete passive electrical component (5) being a part of a sensor (7) of a physical variable.

6. Circuit arrangement in accordance with one of claims 1 to 5, with the semiconductor component being a power semiconductor component.
7. Circuit arrangement in accordance with claim 6, with the power semiconductor component being selected from the MOSFET, IGBT and/or bipolar transistor group.
8. Method for producing a circuit arrangement in accordance with one of claims 1 to 7, with the method steps:
  - a) production of a semiconductor component on a substrate with an electrical contact surface that is facing away from the substrate, and
  - b) production of the electrical connection line, with the contact surface of the semiconductor component being contacted and the part of the discrete passive electrical component being produced.
9. Method in accordance with claim 8, with, in order to provide the semiconductor component on the substrate the semiconductor component being arranged on the substrate in such a way that the electrical contact is facing away from the substrate, and a layer of electrically insulating material is applied to the semiconductor component and the substrate in such a way that the electrical contact is freely accessible.
10. Method in accordance with claim 8 or 9, with a complete layer of electrically insulating material being first applied and the contact being exposed after the application by opening a window in the layer of electrically insulating material.